



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Ref. No. 000763

2000/10

SLP_ ~~R/S~~-2

Specification

~~SC~~-SLP 01 B

Drawing No.

ISA28250-2

ISA28247-3

ISA28246-3

ISA28248-3

ISA28249-3

FCI Japan K. K.

Electronics Division Engineering Section

Certified by



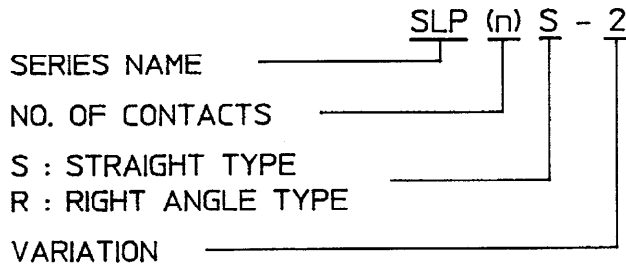
H. Takakura

Manager, Engineering Section

CAT. NO. & DIMENSIONS

NO. OF CONTACTS	STRAIGHT TYPE CAT. NO.	RIGHT ANGLE TYPE CAT. NO.	DIMENSIONS(NOTE 1)	
			A ±0.3	B ±0.1
4	SLP 4S - 2	SLP 4R - 2	11.15	6.45
5	SLP 5S - 2	SLP 5R - 2	12.40	7.70
6	SLP 6S - 2	SLP 6R - 2	13.65	8.95
7	SLP 7S - 2	SLP 7R - 2	14.90	10.20
8	SLP 8S - 2	SLP 8R - 2	16.15	11.45
9	SLP 9S - 2	SLP 9R - 2	17.40	12.70
10	SLP 10S - 2	SLP 10R - 2	18.65	13.95
11	SLP 11S - 2	SLP 11R - 2	19.90	15.20
12	SLP 12S - 2	SLP 12R - 2	21.15	16.45
13	SLP 13S - 2	SLP 13R - 2	22.40	17.70
14	SLP 14S - 2	SLP 14R - 2	23.65	18.95
15	SLP 15S - 2	SLP 15R - 2	24.90	20.20
16	SLP 16S - 2	SLP 16R - 2	26.15	21.45
17	SLP 17S - 2	SLP 17R - 2	27.40	22.70
18	SLP 18S - 2	SLP 18R - 2	28.65	23.95
19	SLP 19S - 2	SLP 19R - 2	29.90	25.20
20	SLP 20S - 2	SLP 20R - 2	31.15	26.45

CAT. NO.

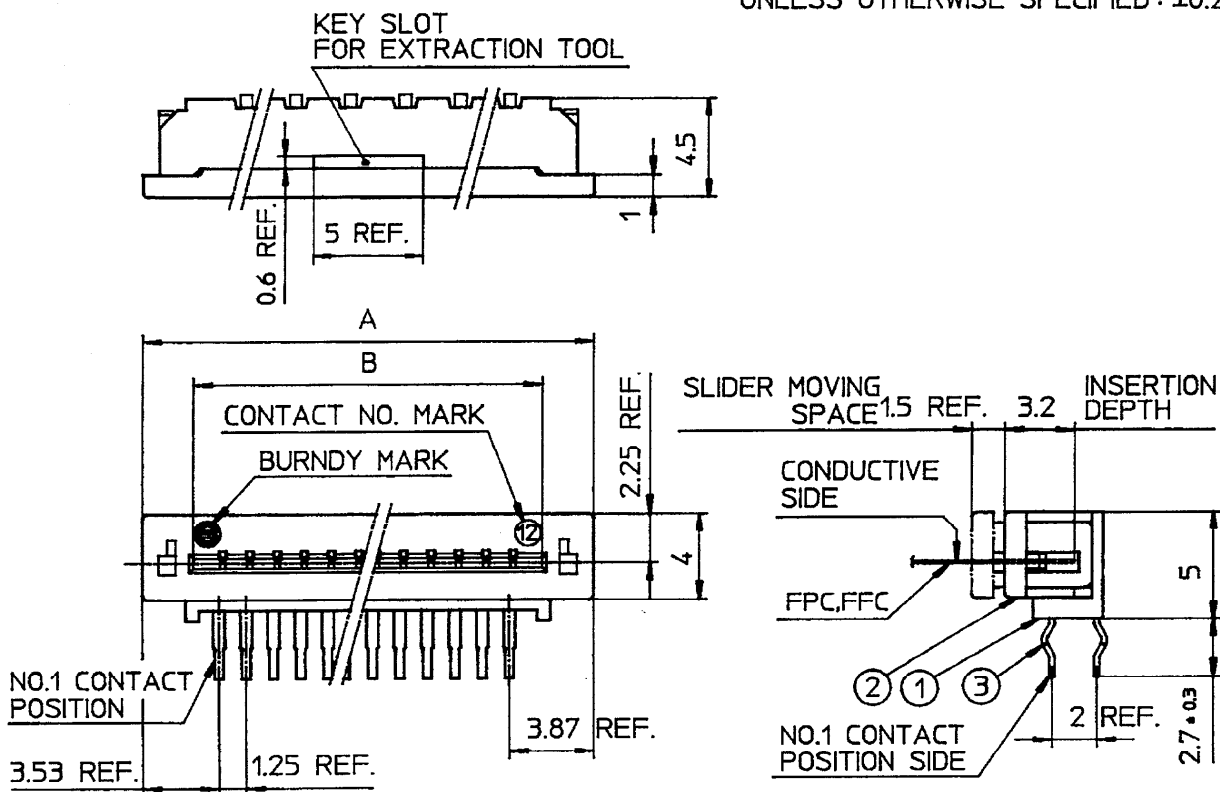


NOTES

- 1) SEE PART DRAWINGS FOR DIMENSIONS A & B

				SCALE	χ	CAT. NO. TABLE FOR LOW PROFILE ZIFLOK	
				DIM. IN	mm	CAT. NO.	
2	'94 8-26	REDRAWN	<i>MDL S.Y.</i>	DESIGNED		SLP__R/S - 2	
REV. DATE		DESCRIPTION	CKD.	DRAWN	<i>MD. Harada</i>	DRAWING NO.	REV.
MATERIAL				CHECKED		JSA 28250	2
				APPROVED	<i>S. Ota</i>		
				DATE	<i>Aug. 26. 1994</i>		

TOLERANCES
UNLESS OTHERWISE SPECIFIED: ±0.2

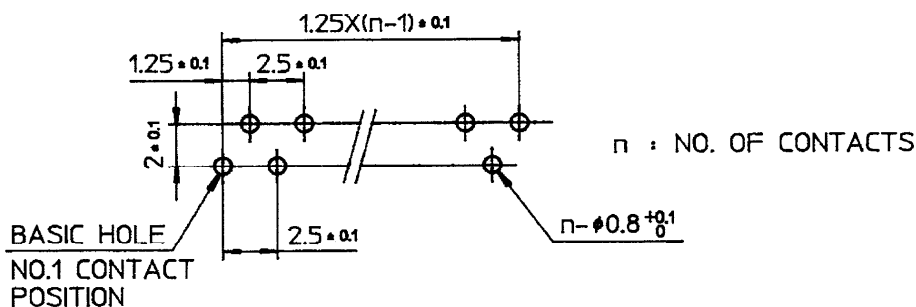


PT. NO.	PARTS NAME	MATERIAL	Q'TY	NOTE
1	HOUSING	PET RESIN GLASS REINFORCED (UL94V-0)	1	COLOR : BLACK
2	SLIDER		1	COLOR : GRAY
3	CONTACT	PHOSPHOR BRONZE	n	PLATING : TIN ALLOY

n : NO. OF CONTACTS

RECOMMENDED PC BOARD

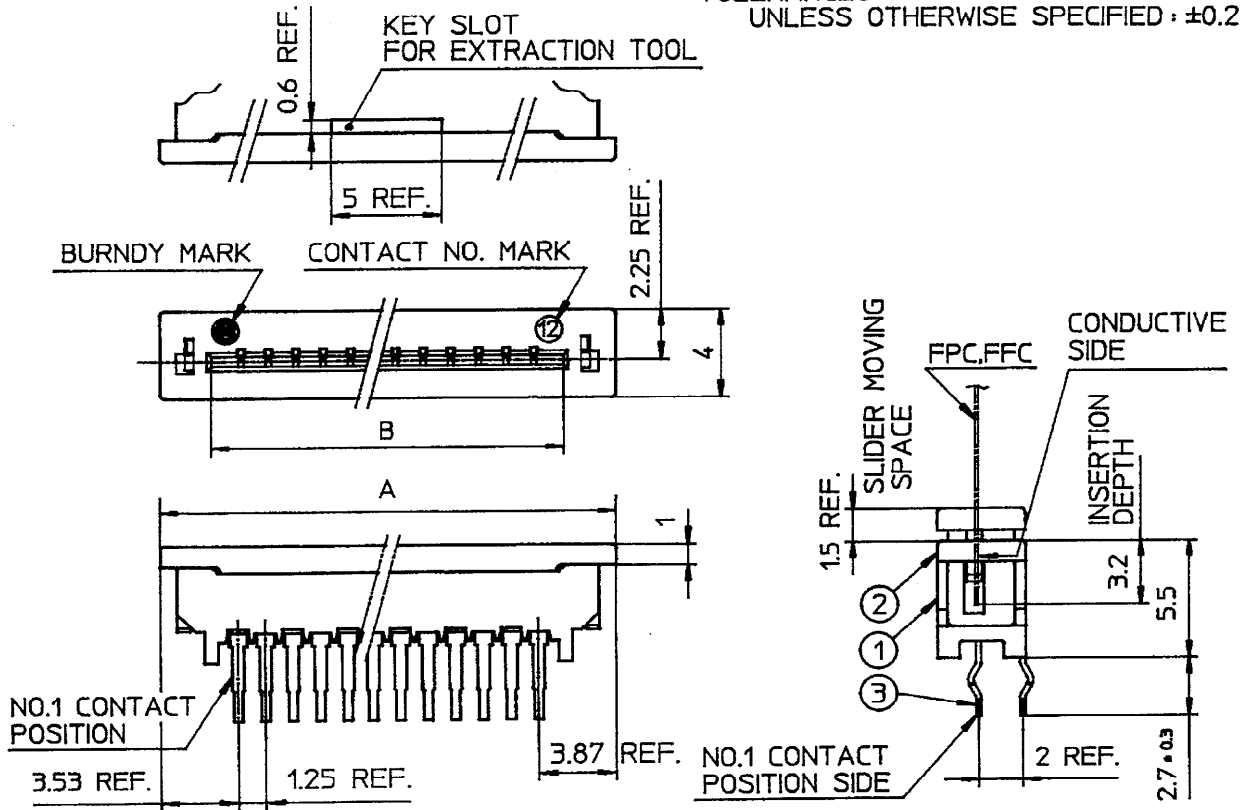
THICKNESS : 0.8-1.6
HOLE PATTERN (COMPONENT SIDE)



				SCALE	×	LOW PROFILE ZIFLOK (RIGHT ANGLE TYPE)	
				DIM. IN	mm	CAT. NO.	
3	'95 1-17	REDRAWN <i>m.o.</i>	<i>Sy</i>	DESIGNED	SLP __ R - 2		
REV. DATE	DESCRIPTION	CKD.	DRAWN	<i>M. Oga</i>	DRAWING NO.	JSA 28247	REV.
MATERIAL				CHECKED	<i>M. Harada</i>	3	
				APPROVED	<i>Sy</i>		
				DATE	Jan. 17. 1995		



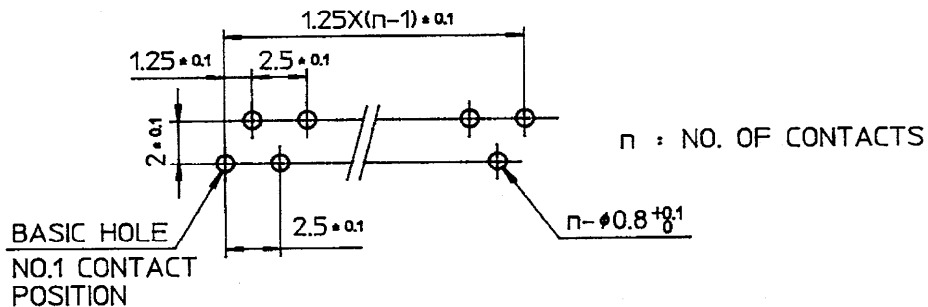
TOLERANCES
UNLESS OTHERWISE SPECIFIED: ±0.2



PT. NO.	PARTS NAME	MATERIAL	Q'TY	NOTE
1	HOUSING	PET RESIN GLASS REINFORCED (UL94V-0)	1	COLOR: BLACK
2	SLIDER		1	COLOR: GRAY
3	CONTACT	PHOSPHOR BRONZE	n	PLATING: TIN ALLOY

n : NO. OF CONTACTS

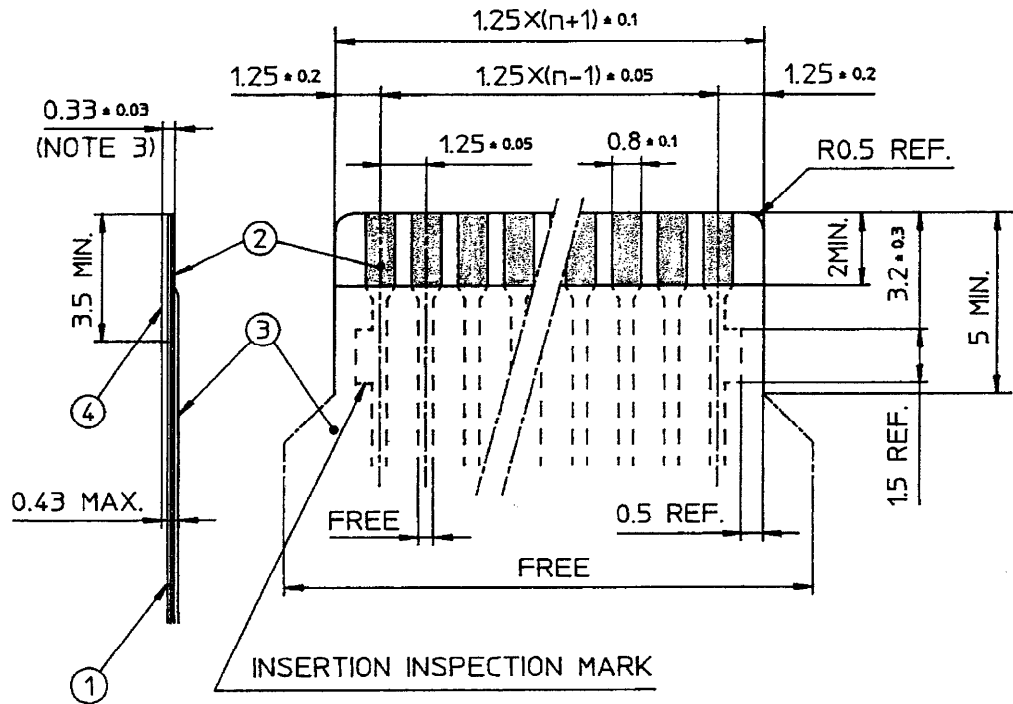
RECOMMENDED PC BOARD
THICKNESS : 0.8-1.6
HOLE PATTERN (COMPONENT SIDE)



REV.	DATE	DESCRIPTION	CKD.	DRAWN	CHECKED	APPROVED	DATE	SCALE	DIM. IN	LOW PROFILE ZIFLOK (STRAIGHT TYPE)	CAT. NO.	DRAWING NO.	REV.
								X	mm				
3	'95 1-17	REDRAWN <i>SM.0</i>	<i>SD</i>									SLP __ S - 2	
				<i>SM.0</i>	<i>mi. Hazuda</i>	<i>S.Yto</i>	<i>Jan. 17, 1995</i>				JSA 28246		3
MATERIAL													

RECOMMENDED CABLE (FPC)

n : NO. OF CONDUCTOR



PT. NO.	PARTS NAME	MATERIAL	THICKNESS (μm)
1	BASE FILM	POLYIMIDE OR EQUAL	25
2	CONDUCTOR	COPPER FOIL (PLATING : SOLDER 1μm MIN. 12μm MAX.)	35
3	OVERLAY	POLYIMIDE OR EQUAL	—
4	SUPPORTING TAPE	POLYESTER OR POLYIMIDE OR EQUAL	188

NOTES.

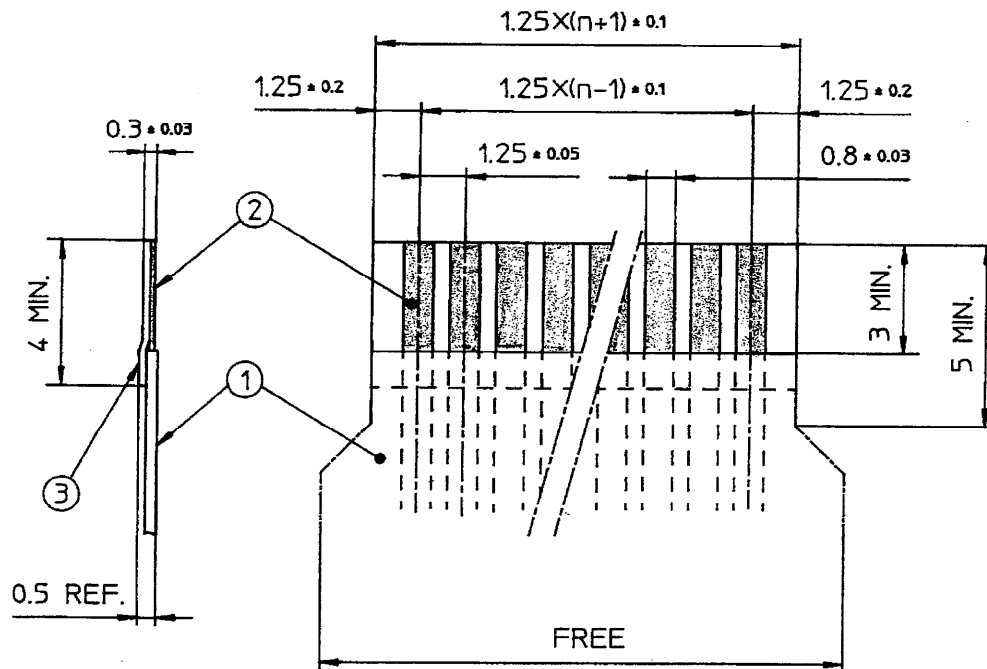
1. NO BURR AT EACH PORTION.
2. NO PEELING IN COMMON USE.
3. TOTAL THICKNESS LIMIT OF EACH MATERIAL (INCLUDING ADHESIVE AGENT) IS SPECIFIED.

REV.	DATE	DESCRIPTION	CKD.	DRAWN	CHECKED	APPROVED	DATE	SCALE	DIM. IN	RECOMMENDED CABLE	CAT. NO.	DRAWING NO.	REV.
3	'99 11-29	PLATING THICKNESS CHANGED. M.I.M.Y H.T.						SCALE	×	RECOMMENDED CABLE			
2	'95 1-13	REDRAWN M.O S.I						DIM. IN	mm				
				DESIGNED						SLP__R/S-2			
				DRAWN	M.Oba					DRAWING NO.			
				CHECKED	M.Harada					JSA 28248			3
				APPROVED	S.Ito								
				DATE	Jan. 13, 1995								



RECOMMENDED CABLE (FFC)

n : NO. OF CONDUCTOR



PT. NO.	PARTS NAME	MATERIAL	NOTE
1	INSULATOR	FLAME RESISTING POLYESTER OR EQUAL	_____
2	CONDUCTOR	COPPER FOIL : 50 μm	PLATING : SOLDER 1 μm MIN.
3	SUPPORTING TAPE	FLAME RESISTING POLYESTER OR EQUAL	_____

NOTES.

1. NO BURR AT EACH PORTION.
2. NO PEELING IN COMMON USE.

REV.	DATE	DESCRIPTION	CKD.	DRAWN	CHECKED	APPROVED	DATE	SCALE	RECOMMENDED CABLE
3	'99 11-29	PLATING THICKNESS CHANGED. M.I M.Y	47	M.Oba	M.Harada	S.Ito	Jan. 17, 1995	SCALE X DIM. IN mm	RECOMMENDED CABLE CAT. NO.
2	'95 1-17	REDRAWN M.O	S.I	M.Oba	M.Harada	S.Ito	Jan. 17, 1995	DESIGNED	SLP__R/S-2
									DRAWING NO. JSA 28249
									REV. 3

